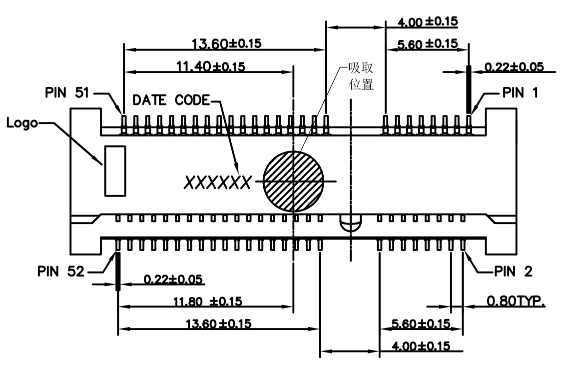
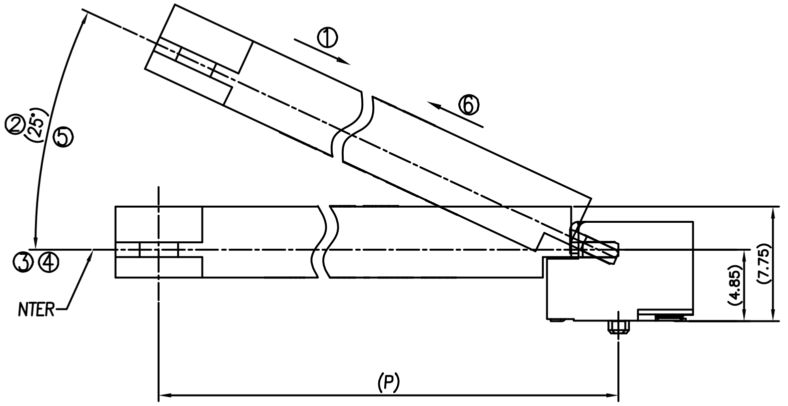
GP Component | HF

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2020/12/01	Ken Lin
A0.1			Change Drawing	2021/11/03	Ken Lin





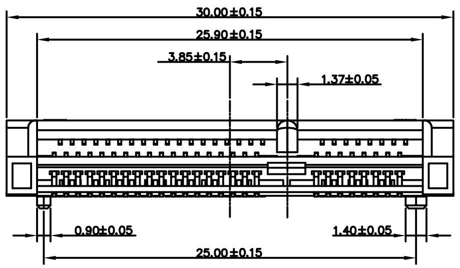
MATING: ① INSERTING(25°) ⟶ ② ROTATING ⟶ ③ FIXED

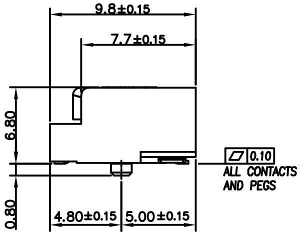
UNMATING: ④ UNFIXED ⟶ ⑤ ROTATING ⟶ ⑥ WITHDRAWING

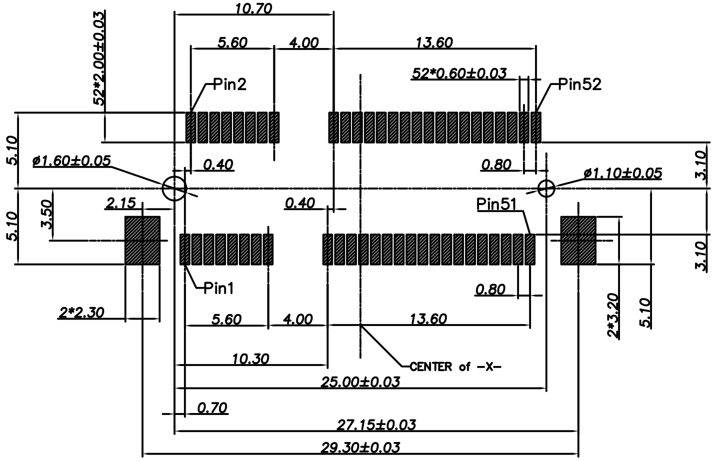
NOTES:
1.MATERIAL:
HOUSING:THERMOPLASTIC,BLACK COLOR,
FLAM RESISTANCE UL94–V0.
CONTACTS:COPPER ALLOY,THICKNESS 0.20mm.
SOLDER PEGS:COPPER ALLOY,THICKNESS 0.20mm.

2.MSL LEVEL:
MSL(MOISTUER SENSITMTY LEVELS)=1

3.FINISHED:
CONTACTS:GOLD FLASH PLATING ON CONGTACT AREA AND
50~120u" MATTE TIN PLATING ON SILDER AREA.
30~120u" NICKEL UNDER–PLATING OVER ALL.
SOLDER PEGS:50~120u" MATTE TIN PLATING OVER,
50~120u" NICKEL UNDER–PLATING OVER ALL.
4.COMPLIANT TO HALOGEN FREE.

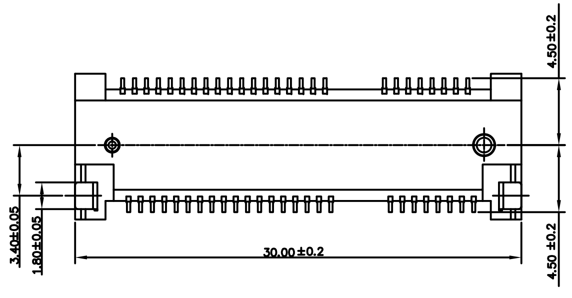






A0.1 RECOMMEND PCB LAYOUT(MINIMUM THICKNESS OF THE PCB IS 0.8mm)

(OTHER TOLERANCES ARE NOT MARKED:±0.03)



MATRIX PART NO:

MST 52 – 01 – 111

MATRIX MINI PCIE

Pin Number

Plating
01:Gold Flash
15:15u"
30:30u"

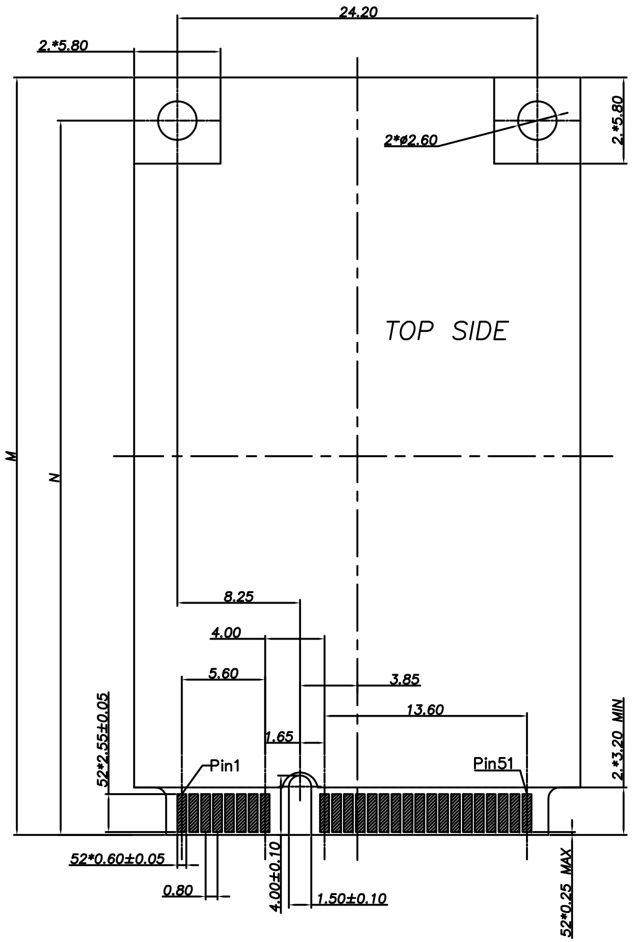
Series Number

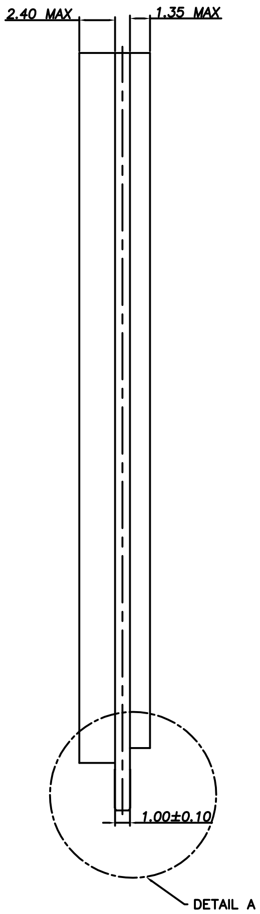
Matrix Electronics Co.,Ltd

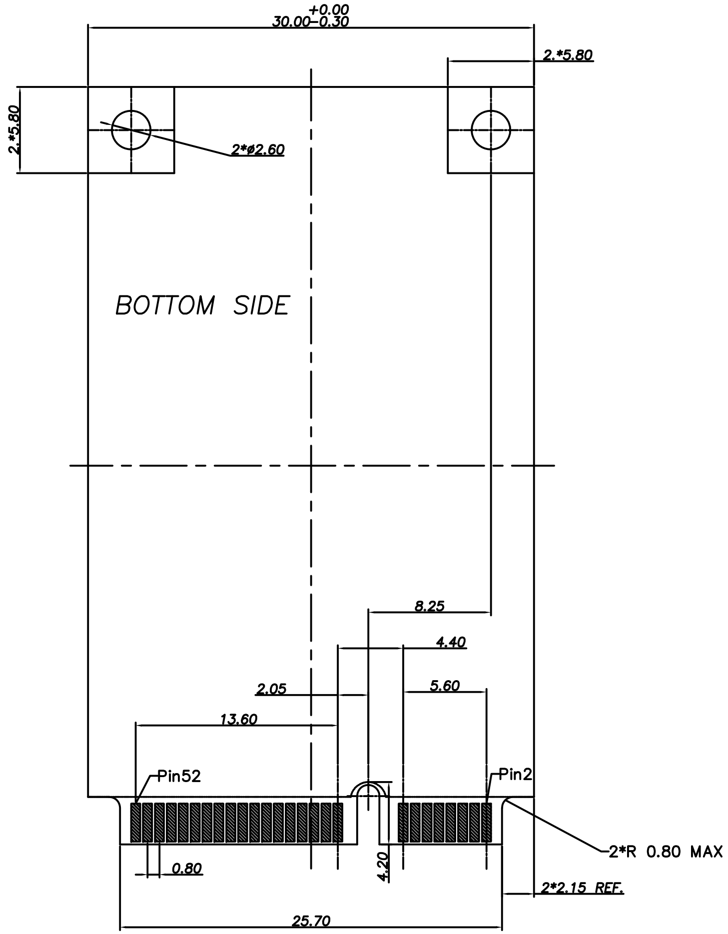
TOLERANCE: X. ±0.35 X.X ±0.25 X.XX ±0.20 X.XXX ±0.10 ANGLE: ±3°	DESIGN BY : Ken Lin	DATE : 2021/11/03	PART NAME: Mini PCI EXPRESS 6.8H Connector	
	CHECKED BY: Vicky Hsieh	DATE : 2021/11/03	PART NO.	MST52–01–111
UNIT: mm [inch]	APPROVED BY1: Richard Hsieh	DATE : 2021/11/03	MOLD NO.	NA
SCALE:1:1 SIZE:A4	APPROVED BY2: Richard Hsieh	DATE : 2021/11/03	DRAW NO. SHEET NO.	 1 OF 2

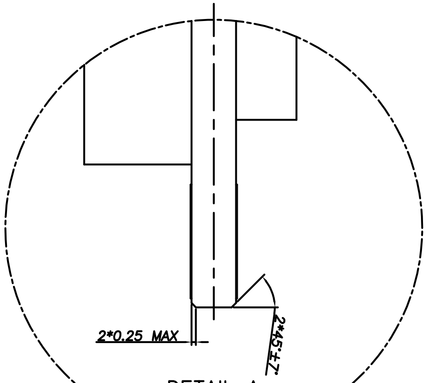
GP Component | HF

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2020/12/01	Ken Lin
A0.1			Change Drawing	2021/11/03	Ken Lin









DETAIL A
SCALE 3:1

	M	N	(P)
FULL-MINI CARD	50.95	48.05	(48.05)
HALF-MINI CARD	26.8	23.9	(23.9)

Matrix Electronics Co.,Ltd

TOLERANCE: X: ±0.35 X.X ±0.25 X.XX ±0.20 X.XXX ±0.10 ANGLE: ±3°	DESIGN BY : Ken Lin	DATE : 2021/11/03	PART NAME: Mini PCI EXPRESS 6.8H Connector	
	CHECKED BY: Vicky Hsieh	DATE : 2021/11/03	PART NO.	MST52-01-111
UNIT: mm [inch]	APPROVED BY1: Richard Hsieh	DATE : 2021/11/03	MOLD NO.	NA
SCALE:1:1 SIZE:A4	APPROVED BY2: Richard Hsieh	DATE : 2021/11/03	DRAW NO.	
			SHEET NO.	2 OF 2